505588601 07/24/2019

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1 EPAS ID: PAT5635401

Stylesheet Version v1.2

 SUBMISSION TYPE:
 NEW ASSIGNMENT

 NATURE OF CONVEYANCE:
 ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Yi-Chun Shih	07/22/2019
Shun-Min Yeh	07/22/2019

RECEIVING PARTY DATA

Name:	GLC SEMICONDUCTOR GROUP (CQ) CO., LTD.		
Street Address: New&Hi-Tech Industry Development Area, Dazu District			
City:	Chongqing City		
State/Country:	CHINA		

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	16521585

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ATTORNEY DOCKET NUMBER: GLCP0003USA

NAME OF SUBMITTER: KATE YEH

SIGNATURE: /KATE YEH/

DATE SIGNED: 07/24/2019

Total Attachments: 4

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PATENT 505588601 REEL: 049853 FRAME: 0995

COMBINE DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION USING AN APPLICATION DATA SHEET (37 CFR 1.76) AND ASSIGNMENT

Title of Invention: MANUFACTURING METHOD OF SEMICONDUCTOR DEVICE

		 Section 1. 		
As the below named inventor, I here This declaration is directed to:	eby declare that:			
☑ The attached application, or				
☐ United States application nu	ımber		filed on	, or
☐ PCT international application	n number		filed on	
The above-identified application was	s made or authorize	ed to be made t	by me.	
I believe that I am the original invent application.	or or an original joi	nt inventor of a	claimed invention	in the
I hereby acknowledge that any willfu under18 U.S.C. 1001 by fine or impr	l false statement n isonment of not mo	ade in this dec ore than five (5)	laration is punisha years. or both.	ble
In consideration of the payment by	GLC SEMICON (CQ) CO., LTD		ROUP having a	postal address of
New&Hi-Tech Industry Develo	opment Area, D	azu District,	Chongqing Cit	y, P.R.C.
(referred to as "ASSIGNEE" below) to acknowledged, andfor other good ar	o I of the sum of Oi nd valuable conside	ne Dollar (\$ 1.0 tration.	0), the receipt of w	hich is hereby
I hereby sell, assign and transfer to a the entire right, title and interest in a invention as above-identified applica- invention by the above application of substitutes, or extensions thereof, ar	nd to any and all in ition and, in and to, r any continuations	provements wi all Letters Pate continuation-i	hich are disclosed ent to be obtained n-part, divisions, re	in the for said enewals
l hereby covenant that no assignment entered into which would conflict with	nt, sale, agreement h this assignment;	or encumbran	ce has been or wil	l be made or
I further covenant that ASSIGNEE wand documents relating to said inver known and accessible to I and will te related thereto and will promptly exe	ntion and said Lette estify as to the sam	rs Patent and I e in any interfer	egal equivalents a ence. litigation pro	s may be
representatives any and all papers, i maintain, issue and enforce said app equivalents thereof which may be ne IN WITNESS WHEREOF, I have her	olication, said inver ecessary or desirab	tion and said L le to carry out t	etters Patent and a he proposes there	said eof.
Note: An application data sheet (PT0 inventive entity, must accompany thi	D/SB/14 or equivales form. Use this for	ent), including r m for <u>each add</u>	naming the entire	

Page 1 of 4

NPO#GLC-P0003-USA:0 CUST# F#NPO-P0002F-US1201 DSB0-108U023815

Docket No. GLCP0003USA

LEGAL NAI	ME OF INVENTOR(ASSIGNOR)			
Inventor:	Yi-Chun Shih	Date:	2019, 7, 22	
Signature:	Ti-Chun Shih			

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F#NPÖ-P0002E-US1201 DSB0-108U023815

\PO#GLC-P0003-U\$A:0 UUST=

> PATENT REEL: 049853 FRAME: 0997

COMBINE DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION USING AN APPLICATION DATA SHEET (37 CFR 1.76) AND ASSIGNMENT

Title of Invention: MANUFACTURING METHOD OF SEMICONDUCTOR DEVICE

NPO#GLC-P0003-USA:0

CUST#

As the below named inventor, I hereby diffused the control of the	eclare that:			
☐ The attached application, or				
☐ United States application number	er		filed on	, or
☐ PCT international application nu	ımber		filed or	
The above-identified application was ma	de or autho	rized to be	made by me.	
I believe that I am the original inventor o application.	r an original	joint inven	or of a claimed inv	ention in the
I hereby acknowledge that any willful fall under18 U.S.C. 1001 by fine or imprison				
In consideration of the payment by GL (C	.C SEMIC Q) CO., L		OR GROUP hav	ring a postal address of
New&Hi-Tech Industry Developm	nent Area	, Dazu Di	strict, Chongqir	ng City, P.R.C.
(referred to as "ASSIGNEE"below) to I o acknowledged, andfor other good and ve	f the sum of aluable cons	f One Dolla sideration.	r (S 1.00), the rece	pt of which is hereby
I hereby sell, assign and transfer to ASS the entire right, title and interest in and transfer to as above-identified application invention by the above application or an substitutes, or extensions thereof, and a	o any and a and, in and y continuati	ll improvem I to, all Lette ons, contine	ents which are dis ers Patent to be ob aation-in-part, divis	closed in the tained for said ions, renewals,
I hereby dovenant that no assignment, sentered into which would conflict with the			umbrance has beei	or will be made or
I further covenant that ASSIGNEE will, used documents relating to said invention known and accessible to I and will testify related thereto and will promptly executed.	n and said L y as to the s	etters Pate ame in any	nt and legal equiva interference, litiga	lents as may be
representatives any and all papers, instraintain, issue and enforce said applicate equivalents thereof which may be necestal WITNESS WHEREOF, I have hereur	ation, said in ssary or des	ivention and irable to ca	d said Letters Pate rry out the propose	nt and said s thereof.
Note: An application data sheet (PTO/S inventive entity, must accompany this for	B/14 or equ orm. Use this	ivalent), inc s form for <u>e</u>	luding naming the ach additional inve	entire ntor.
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PATENT REEL: 049853 FRAME: 0998

F#NPO-P0002E-US1201

DSB0-108U023815

Docket No. GLCP0003USA

LEGAL NAME OF INVENTOR(ASSIGNOR)				
Inventor:	Shun-Min Yeh	Date:	2019,7,>2	
Signature:		Min Jeh		

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NPO#GLC-P0003-USA:0 CUST#

RECORDED: 07/24/2019

F#NPO-P0002E-US1201 DSB0-108U023815

PATENT REEL: 049853 FRAME: 0999